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Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Obsahuje: EN 60286-4:2013, IEC 60286-4:2013

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60286-4

November 2013

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Supersedes EN 60286-4:1998

English version

**Packaging of components for automatic handling -
Part 4: Stick magazines for electronic components encapsulated in
packages of different forms
(IEC 60286-4:2013)**

Emballage des composants pour
opérations automatisées – Partie 4:
Magasins chargeurs pour composants
électroniques encapsulés dans des
boîtiers de différentes formes
(CEI 60286-4:2013)

Gurtung und Magazinierung von Bauteilen
für automatische Verarbeitung -
Teil 4: Stangenmagazine für elektronische
Bauelemente mit verschiedenen
Gehäusen
(IEC 60286-4:2013)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 40/2230/FDIS, future edition 3 of IEC 60286-4, prepared by IEC TC 40, "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60286-4:2013.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2014-05-30
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2016-08-30

This document supersedes EN 60286-4:1998.

EN 60286-4:2013 includes the following significant technical changes with respect to EN 60286-4:1998:

Clause 4 describes the guidelines for customer specific stick magazine design. It replaces the magazine design rules for IEC outlined components and rules for orientation of components in stick magazines which have been moved to Annexes Z to D.

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The text of the International Standard IEC 60286-4:2013 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

ISO 11469 NOTE Harmonized as EN ISO 11469.

Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-3	1999	Mechanical standardization of semiconductor devices - Part 3: General rules for the preparation of outline drawings of integrated circuits	EN 60191-3	1999
IEC 60747-1 + corr. August + A1	2006 2008 2010	Semiconductor devices - Part 1: General	-	-



INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Packaging of components for automatic handling –
Part 4: Stick magazines for electronic components encapsulated in packages of
different forms**

**Emballage des composants pour opérations automatisées –
Partie 4: Magasins chargeurs pour composants électroniques encapsulés dans
des boîtiers de différentes formes**





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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 4: Stick magazines for electronic components encapsulated
in packages of different forms****FOREWORD**

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International Standard IEC 60286-4 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This third edition cancels and replaces the second edition published in 1997 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- Clause 4 describes the guidelines for customer specific stick magazine design. It replaces the magazine design rules for IEC outlined components and rules for orientation of components in stick magazines which have been moved to Annexes A to D.

The text of this standard is based on the following documents:

FDIS	Report on voting
40/2230/FDIS	40/2241/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60286 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 4: Stick magazines for electronic components encapsulated
in packages of different forms****1 Scope**

This part of IEC 60286 is applicable to stick magazines (including end stoppers) intended to be used for storage of electronic components, for transport from the manufacturer to the customer and for in-house use in the manufacturing plant. They are also used to feed automatic placement machines for surface mounting as well as for through-hole mounting of electronic components.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-3:1999, *Mechanical standardization of semiconductor devices – Part 3: General rules for the preparation of outline drawings of integrated circuits*

IEC 60747-1:2006, *Semiconductor devices – Part 1: General*
Amendment 1:2010

koniec náhľadu – text d'alej pokračuje v platenej verzii STN